

# COM-SKUC6

## Thermal Image Analysis Report

Summary	<input type="checkbox"/> <b>Pass</b> <input type="checkbox"/> <b>Fail</b> <input checked="" type="checkbox"/> <b>Pass with Deviation</b> <b>Comment:</b> <u>There are three temperature point marginal passed, the functions are stable.</u>			
	Test Result Summary			
	Critical	Major	Minor	Enhancement
Defect Found	0	0	0	3
Defect Unsolved	0	0	0	0

Issue date	QE Manager	Test Engineer
2016 / 05 / 03	KJ Wang	Ben Sun

## Sample Configuration & Quantity Under Test

- **Model name : COM-SKUC6 A0.3**
- **CPU : Intel i7-6600 2.6GHz**
- **Memory : Transcend DDR3L-1600 8GB**
- **2.5" SATA HDD : WD WD5800BEVT 250GB**
- **BIOS : R0.8**
- **Test Software : Windows 8 / Run PassMark Burn In Test 8.1 Pro**
- **Power : ATX Power**
- **Heat Sink & Fan :**



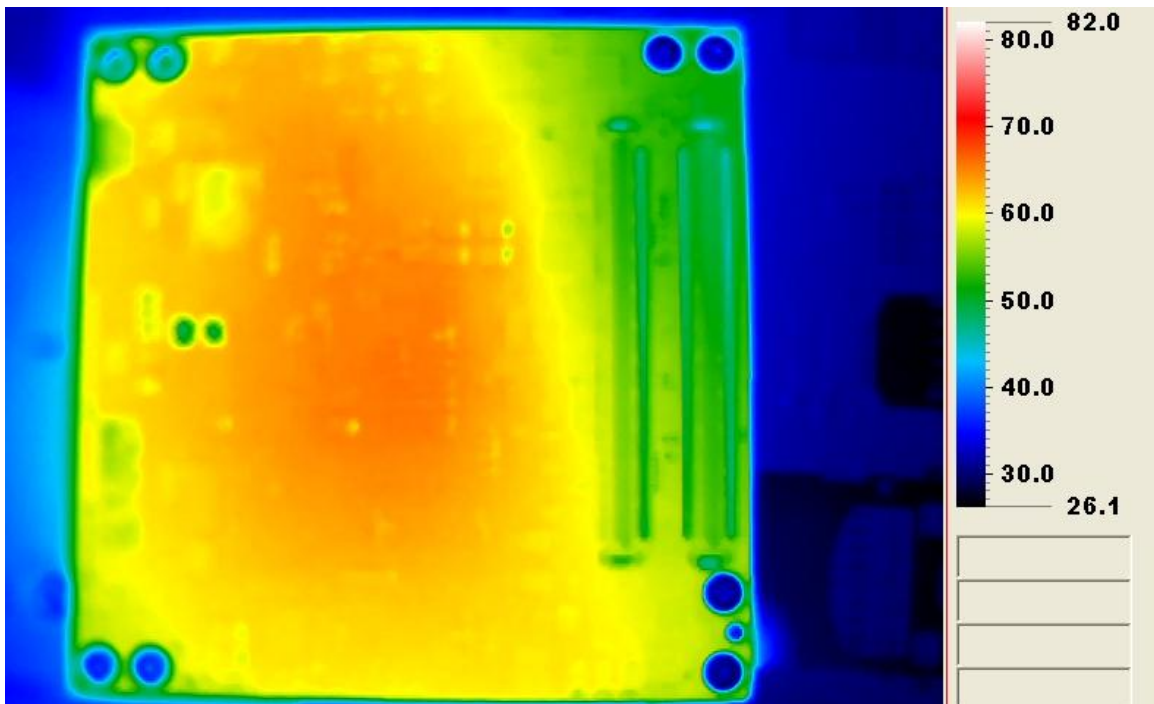
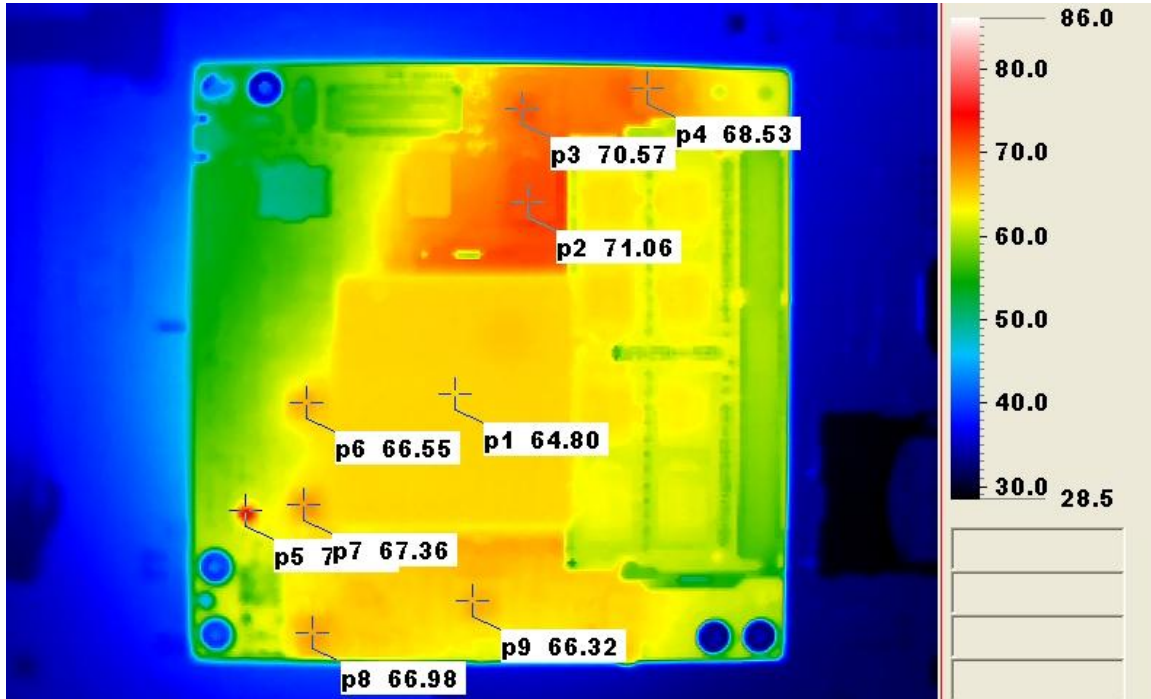
# Thermal Image Analysis

1. Test Date: 2015-04-29
2. Test Product: COM-SKUC6 A0.3
3. Test Site: AAEON QE Dept.
4. Temperature Measurement:
  - 4.1. 40 Channel Thermal Recorder:
    - 4.1.1 YOKOGAWA Inc,
    - 4.2.2 Model: DA100-13-1D  
Date of Calibration: 2015/09/10  
Serial Number: 12A323190
  - 4.2. IR Scanner: Infrared Camera
    - 4.2.1 NEC Avio Infrared Technologies Co., Ltd.
    - 4.2.2 Model: Thermo GEAR G100W2-D  
Date of Calibration: 2015/12/01  
Serial Number: 1051444
5. Test Condition:

Test by DA-100: 25.3°C with Heat Sink & Fan
6. Take Picture Time:

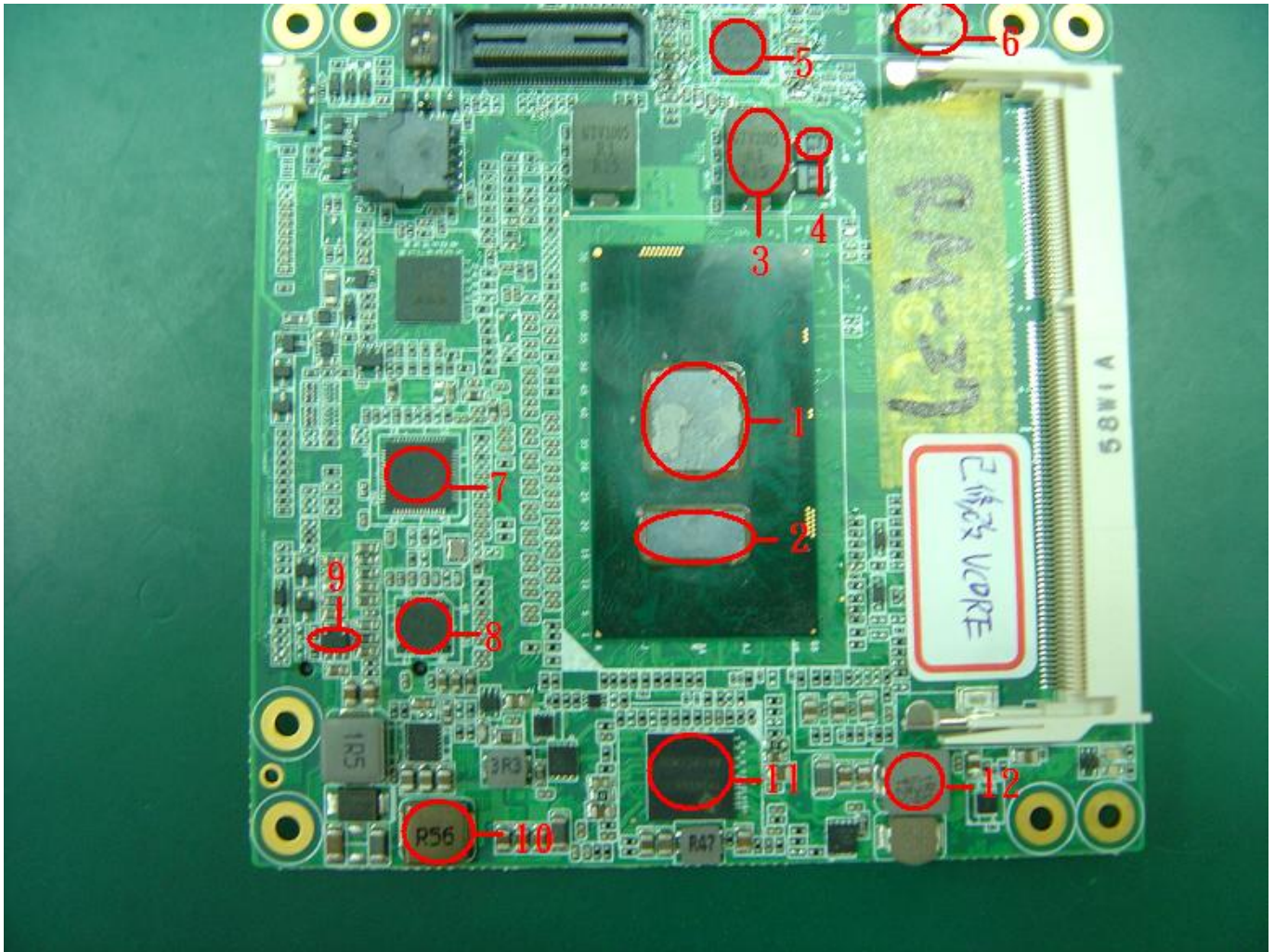
After power on 2 hours

**Temperature Profile Test:**  
**Component Side:**



**Terminal Recorder:**

Measuring Thermal Couple Position :



Using YOKOGAWA / DARWIN DA100-100-13-1D test

Point	Position	Describe	Tc (*1) (°C)	TAT(*2)	TPT(*3)	Note
				26.0°C	60°C	
1	U7	(TF)INTEL CPU.SKYLAK-U SERIES.BGA1356P.SMD	100	41.0	75.0	
2	U7	(TF)INTEL CPU.SKYLAK-U SERIES.BGA1356P.SMD	100	39.8	73.8	
3	L10	(TF)INDUCTOR.0.15uH.10%.DCR=0.39±5% mohm.IDC=53A. 10.2x7x4.95mm.SMD.GOTREND.GTV1005PR1-R15K	125	51.1	85.1	
4	C669	(TF)CAP.330uF.2.5V.20%.B2(3.5*2.8*1.9mm).SMD.9mohm. NEC-TOKIN.TEPSGB20E337M9-8R	125	52.6	86.6	
5	U38	(TF)IC.3-Rail Controller.with SVID Interface for IMVP8.QFN 52.SMD.ON Semi.NCP81246MNTXG	125	52.8	86.8	
6	L11	(TF)COIL.0.36uH.DCR=1.35mohm.Irms=20Amp.20%.SMD.8 .7*7.0*4.0mm. Panasonic.ETQP4LR36AFM	130	50.0	84.0	
7	U1	(TF)IC.Display Port to LVDS Converter.QFN 56 Pin.SMD.NXP.PTN3460BS	85	48.5	82.5	NOTE1
8	U6	(TF)IC.DisplayPort to VGA Converter.QFN 40P.SMD.Chrontel.CH7517A-BF	85	45.7	79.7	NOTE1
9	U3	(TF)IC.LDO Regulator.500mA.SOT23-5 5P.SMD.UPI.UP0107BMA5-00	100	50.8	84.8	
10	L19	(TF)COIL.0.56uH.DCR=5mohm.Idc=15.5Amp.20%.SM	125	47.7	81.7	
11	U56	(TF)IC.PMIC.Intel skylake.NFBGA.159P.SMD.TI.TPS650830ZCGR	100	45.1	79.1	
12	L14	(TF)COIL.1.0uH.DCR=7.4mohm.Idc=12Amp.20%.SMD.6.6x7 .3x3.0mm.CYNTEC PCMB063T-1R0MS	125	45.2	79.2	
		RAM	85	49.3	83.3	NOTE1

Note(\*):

- "Tc" indicates the component's case maximum temperature value specified in its datasheet.
  - "TAT" indicates the actual measured temperature under product specification.
  - "TPT" indicates the predicted temperature under 25°C working environmental.
  - Judgment Criteria:**
    - **Fail** :  $T_m > T_c + 5^\circ\text{C}$ ; The measured value is over specification plus margin.
    - **Margin** :  $T_c + 5^\circ\text{C} > T_m > T_c - 10^\circ\text{C}$ ; The measured value is within specification with margin.  
For FANLESS system application, it is strongly recommended to add thermal dissipation design for better reliability.
    - **Pass** :  $T_m < T_c - 10^\circ\text{C}$ ; The measured value is with safety margin.
  - RTC battery avoid to put on heat position. Please do not exceed battery temperature specification.
4. Defect NO. [C150201QED01](#)